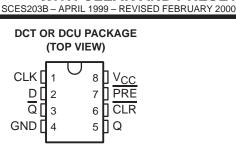
- EPICTM (Enhanced-Performance Implanted CMOS) Submicron Process
- I_{off} Supports Partial-Power-Down Mode Operation
- Supports 5-V V_{CC} Operation
- Package Options Include Plastic Thin Shrink Small-Outline (DCT, DCU) Packages



description

This single positive-edge-triggered D-type flip-flop is designed for 1.65-V to 5.5-V V_{CC} operation.

A low level at the preset (PRE) or clear (CLR) input sets or resets the outputs, regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

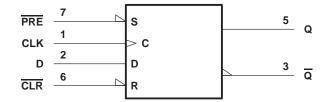
This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The SN74LVC2G74 is characterized for operation from -40°C to 85°C.

	FUNCTION TABLE									
	INP	OUTI	PUTS							
PRE	CLR	CLK	D	Q	Q					
L	Н	Х	Х	Н	L					
н	L	Х	Х	L	Н					
L	L	Х	Х	н†	н†					
н	Н	\uparrow	Н	н	L					
н	Н	\uparrow	L	L	Н					
н	Н	L	Х	Q ₀	\overline{Q}_0					

[†] This configuration is nonstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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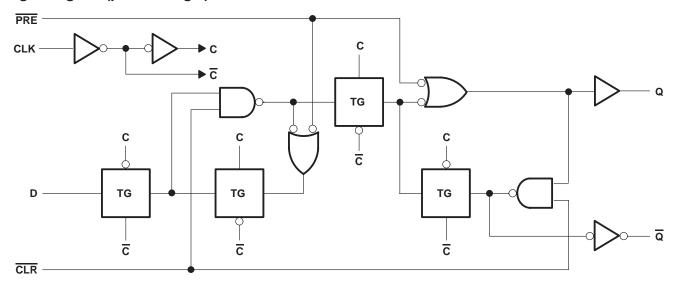
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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 6.5 V
Input voltage range, V _I (see Note 1)	–0.5 V to 6.5 V
Output voltage range, V _O (see Notes 1 and 2)	–0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, I _O	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 3): DCT package	
DCU package	329°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The value of V_{CC} is provided in the recommended operating conditions table.

3. The package thermal impedance is calculated in accordance with JESD 51.



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recommended operating conditions (see Note 4)

			MIN	MAX	UNI
Vaa	Supply voltage	Operating	1.65	5.5	V
Vcc	Supply voltage	Data retention only	1.5		v
		V _{CC} = 1.65 V to 1.95 V			
.,		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
VIН	High-level input voltage	ligh-level input voltage V _{CC} = 3 V to 3.6 V 2		v	
		$V_{CC} = 4.5 V \text{ to } 5.5 V$	$0.7 \times V_{CC}$		
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
M		level input voltage $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ $V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		0.7	v
VIL	Low-level input voltage			0.8	
		$V_{CC} = 4.5 \text{ V} \text{ to } 5.5 \text{ V}$		$0.3 \times V_{CC}$	
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	VCC	V
		V _{CC} = 1.65 V		-4	
		V _{CC} = 2.3 V		-8	
ЮН	High-level output current	N/		-16	mA
		V _{CC} = 3 V		-24	
		$V_{CC} = 4.5 V$		-32	
		V _{CC} = 1.65 V		4	
		V _{CC} = 2.3 V		8	
IOL	Low-level output current	N/		16	mA
		$V_{CC} = 3 V$		24	
		$V_{CC} = 4.5 V$		32	
		V_{CC} = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V		20	
$\Delta t / \Delta v$	Input transition rise or fall rate	$V_{CC} = 3.3 V \pm 0.3 V$		10	ns/\
		$V_{CC} = 5 V \pm 0.5 V$		5	
TA	Operating free-air temperature	÷	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CONDITIONS	Vcc	MIN	TYP [†]	MAX	UNIT		
		I _{OH} = -100 μA	1.65 V to 5.5 V	V _{CC} -0.1					
VOH		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2					
		$I_{OH} = -8 \text{ mA}$	2.3 V	1.9					
VOH	$I_{OH} = -16 \text{ mA}$		2.4			V			
		I _{OH} = -24 mA	3 V	2.3					
		I _{OH} = -32 mA	4.5 V	3.8					
		I _{OL} = 100 μA	1.65 V to 5.5 V			0.1			
		I _{OL} = 4 mA	1.65 V			0.45			
		I _{OL} = 8 mA	2.3 V			0.3	V		
VOL		I _{OL} = 16 mA	2.1		0.4				
		I _{OL} = 24 mA	3 V			0.55			
		I _{OL} = 32 mA	4.5 V			0.55			
I	Control inputs	VI = 5.5 V or GND	0 to 5.5 V			±5	μΑ		
loff	-	$V_{I} \text{ or } V_{O} = 5.5 \text{ V}$	0			±10	μΑ		
ICC		$V_{I} = 5.5 \text{ V or GND}, \qquad I_{O} = 0$	1.65 V to 5.5 V			10	μΑ		
∆ICC		One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	3 V to 5.5 V			500	μΑ		
Ci		V _I = V _{CC} or GND	3.3 V				pF		

[†] All typical values are at $V_{CC} = 3.3$ V, $T_A = 25^{\circ}$ C.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 4)

			V _{CC} = ± 0.1		۲ <mark>۰۵</mark> × V _{CC} = ± 0.2		= ۷ _{CC} ± 0.3		۲ <mark>۰۵</mark> کا ۲		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclocl	<										MHz
	Dulas duration	CLK									ns
tw	Pulse duration	PRE or CLR low									
4	Coture times hotons CLI/	Data									
t _{su} Setup time before CLK↑		PRE or CLR inactive									ns
t _h Hold time, data after CLK↑										ns	

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 4)

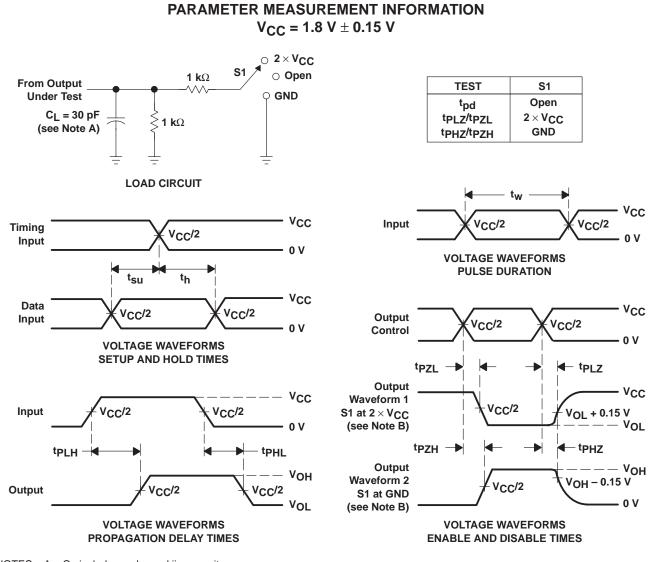
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1		V _{CC} = ± 0.2		V _{CC} = ± 0.		= V _{CC} ± 0.	= 5 V 5 V	UNIT
		(001201)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fmax											MHz
^t pd	CLK	Q									
	PRE or CLR	Q or \overline{Q}									ns



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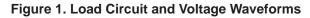
operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		AMETER TEST CONDITIONS		V _{CC} = 1.8 V V _{CC} = 2.5 V		V _{CC} = 5 V	UNIT
		TEST CONDITIONS	TYP	TYP	TYP	ТҮР	UNIT
C _{pd}	Power dissipation capacitance	f = 10 MHz					pF



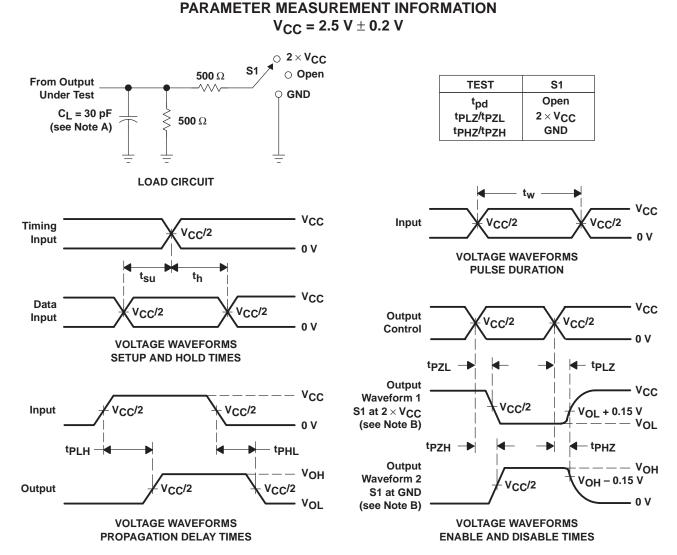
NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2 ns, t_f \leq 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .





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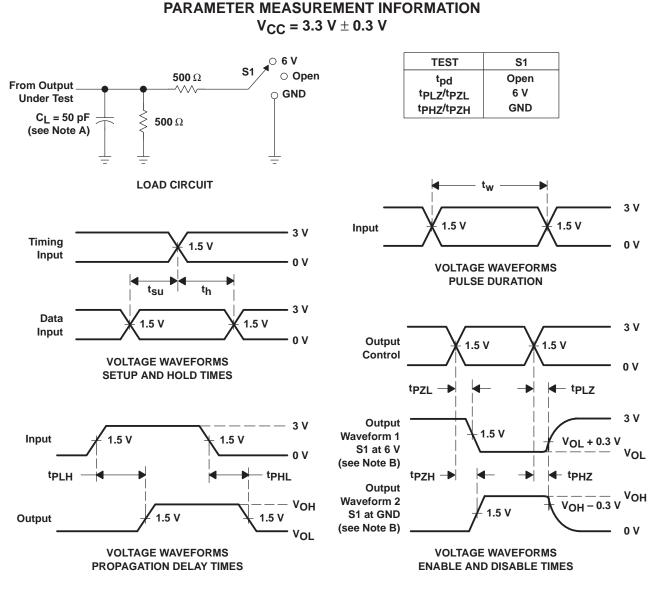


- NOTES: A. Cl includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_Q = 50 Ω, t_f ≤ 2 ns, t_f ≤ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLZ and tpHZ are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tPLH and tPHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



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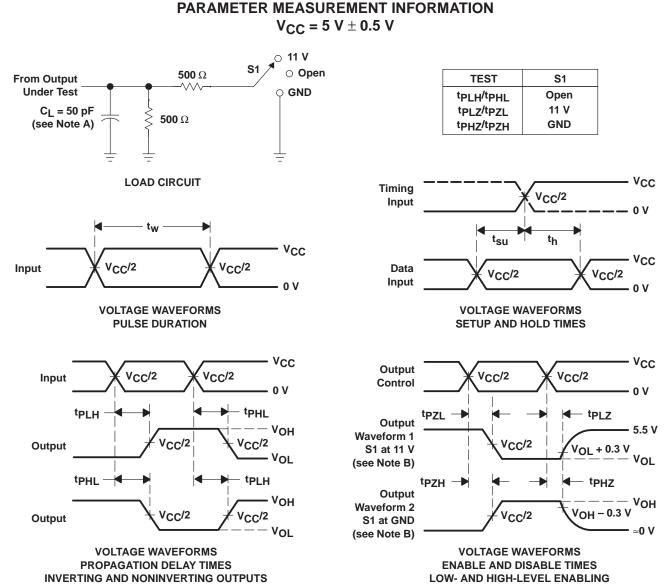
NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. tPLH and tPHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms



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NOTES: A. CL includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 All input pulses are supplied by generators having the following characteristics: PRP < 10 MHz, Za = 50.0, t < 2.5 ns. t < 2.5 ns.

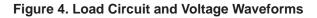
C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.

E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .

F. t_{PZL} and t_{PZH} are the same as t_{en}.

G. tPLH and tPHL are the same as tpd.





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